

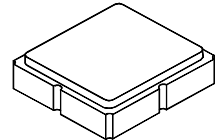


- Low Insertion Loss
- 3.0 X 3.0 X 1.2 mm Surface-Mount Case
- Differential Input and Output
- Complies with Directive 2002/95/EC (RoHS)



SF2079E

251.045 MHz SAW Filter



SM3030-8

Absolute Maximum Ratings

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Maximum DC Voltage Between any Two Terminals	30	VDC
Storage Temperature Range	-60 to +95	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260°C for 30 s	

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_c	1		251.045		MHz
Insertion Loss	IL			12.5	15.0	dB
Amplitude Ripple (p-p)	fc - 6.2500 to fc - 4.3925 MHz	1, 2		1.3	2.0	dB
				0.5	1.5	
				0.5	1.5	
				0.7	1.5	
				0.6	1.5	
				0.9	2.5	
1.5 dB Passband width centered at fc				13.4		MHz
3.0 dB Passband width centered at fc				14.1		
Low Side Attenuation < 234.545 MHz (< fc - 16.5 MHz)			35	38		dB
Low Side Attenuation, 234.545 to 240.545 MHz (fc-10.5 MHz)			32	34		
High Side Attenuation, 260.045 to 267.545 MHz (fc+9.0 MHz)			14	26		
High Side Attenuation > 267.545 MHz (> fc + 16.5 MHz)			30	35		
Temperature Coefficient of frequency					-18	ppm/K
Delay Ripple (p-p)	fc - 6.2500 to fc - 4.3925 MHz	1, 2, 3		44	90	ns
				37	70	
				39	120	
				40	120	
				34	70	
				37	90	
Source/Load Impedance				150		ohms
Case Style		6	SM3030-8 3.0 x 3.0 mm Nominal Footprint			
Lid Symbolization (YY=year, WW=week, S=shift) See note 4			TBD YWWS			



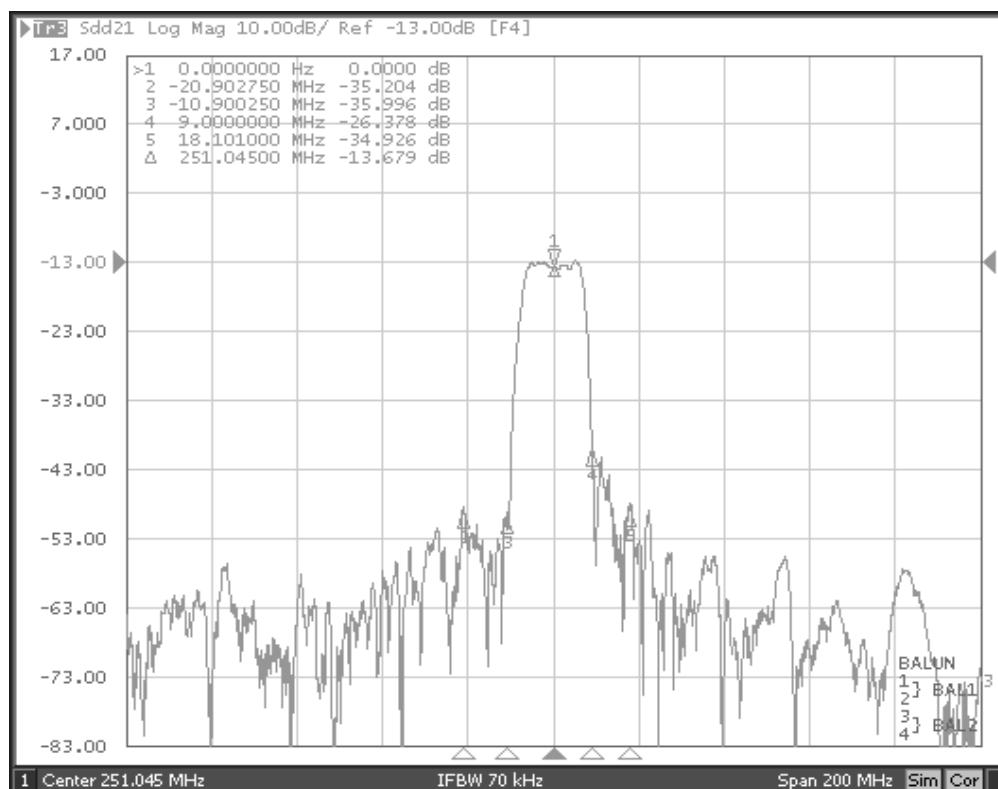
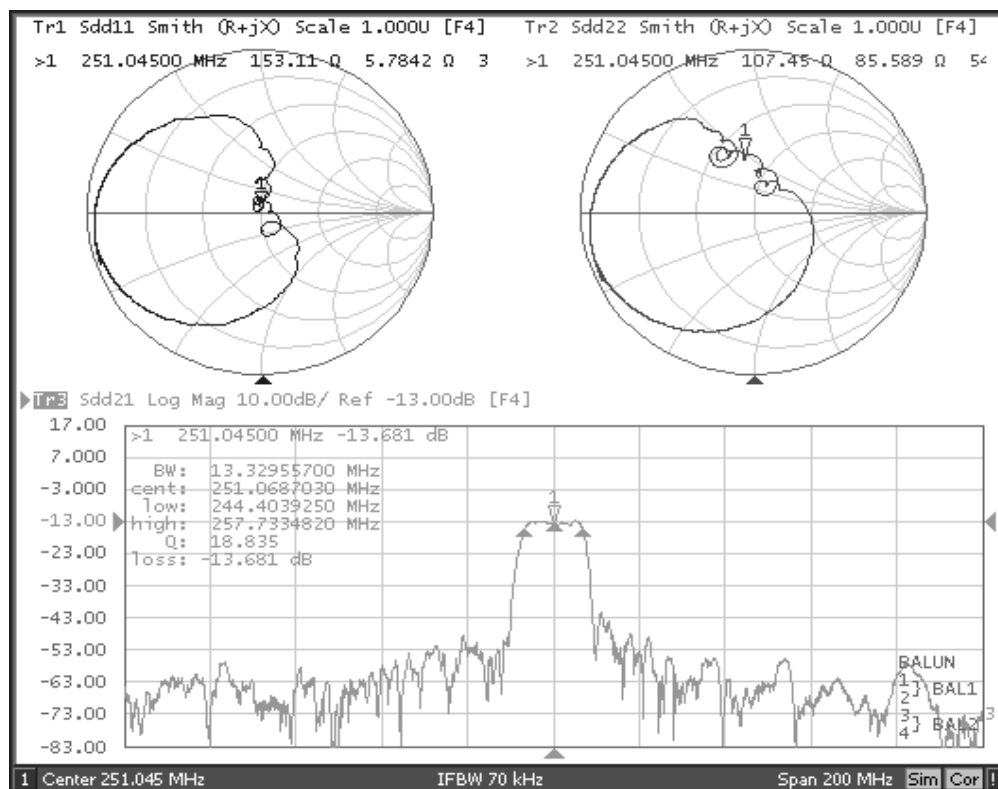
CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

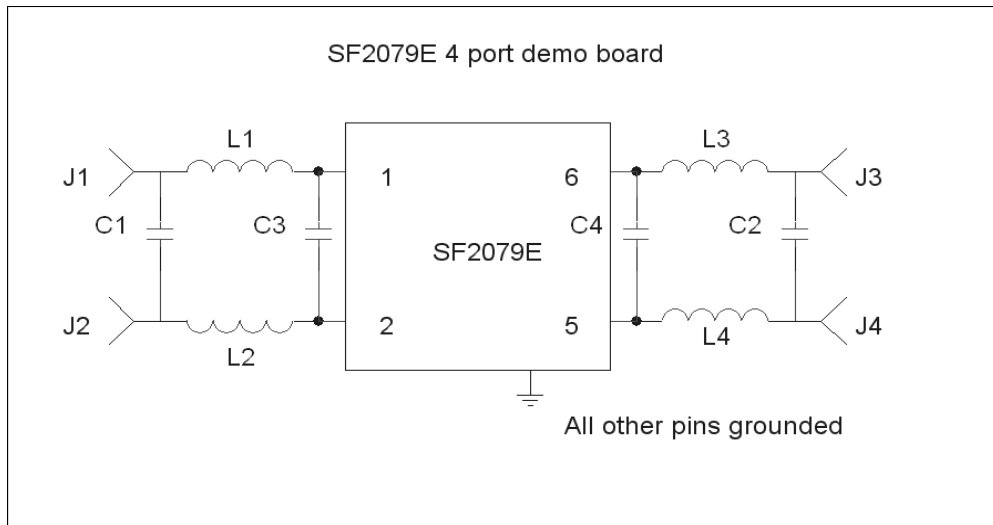
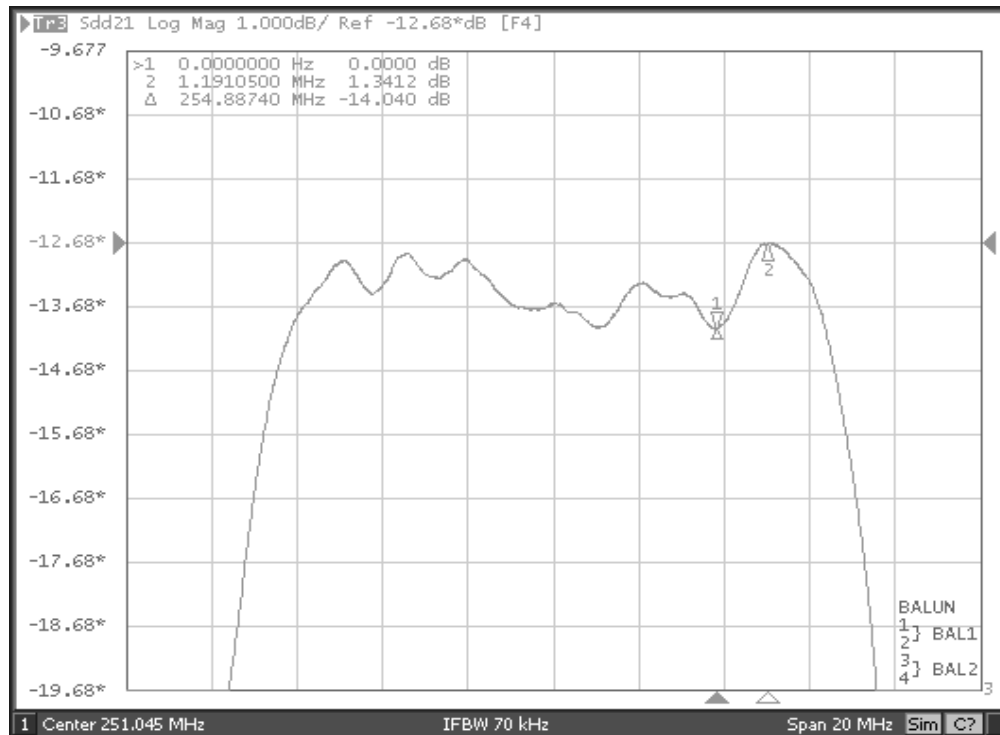
Notes:

Notes:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, fc.
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout

4. and external impedance matching design. See Application Note No. 42 for details.
 5. The design, manufacturing process, and specifications of this filter are subject to change.
 6. Tape and Reel Standard Per ANSI / EIA 481.
 7. US and international patents may apply.
- RFM, stylized RFM logo, and RF Monolithics, Inc. are registered trademarks of RF Monolithics, Inc.



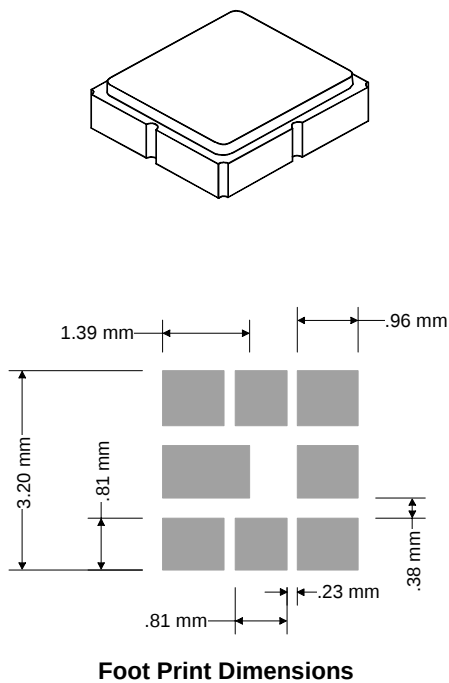


PCB	401-1724-001	PCB, DEMO, 3.0 or 3.8 PKG, PINS 1&2 IN, 5&6 OUT
J1,J2,J3,J4	500-1279-001	CONNECTOR, SMA FEMALE, END LAUNCH, 062" THICK PCB
L1,L2	501-1068-390	INDUCTOR, CHIP, 39 nH 0603
L3,L4	501-1068-470	INDUCTOR, CHIP, 47 nH 0603
C1	501-0857-150	CAPACITOR, CHIP, 15 pF 0402
C2	501-0857-120	CAPACITOR, CHIP, 12 pF 0402
C3	501-0857-010	CAPACITOR, CHIP, 1.0 pF 0402
C4	501-0857-005	CAPACITOR, CHIP, 0.5 pF 0402

SM3030-8 Case

8-Terminal Ceramic Surface-Mount Case

3.0 X 3.0 mm Nominal Footprint

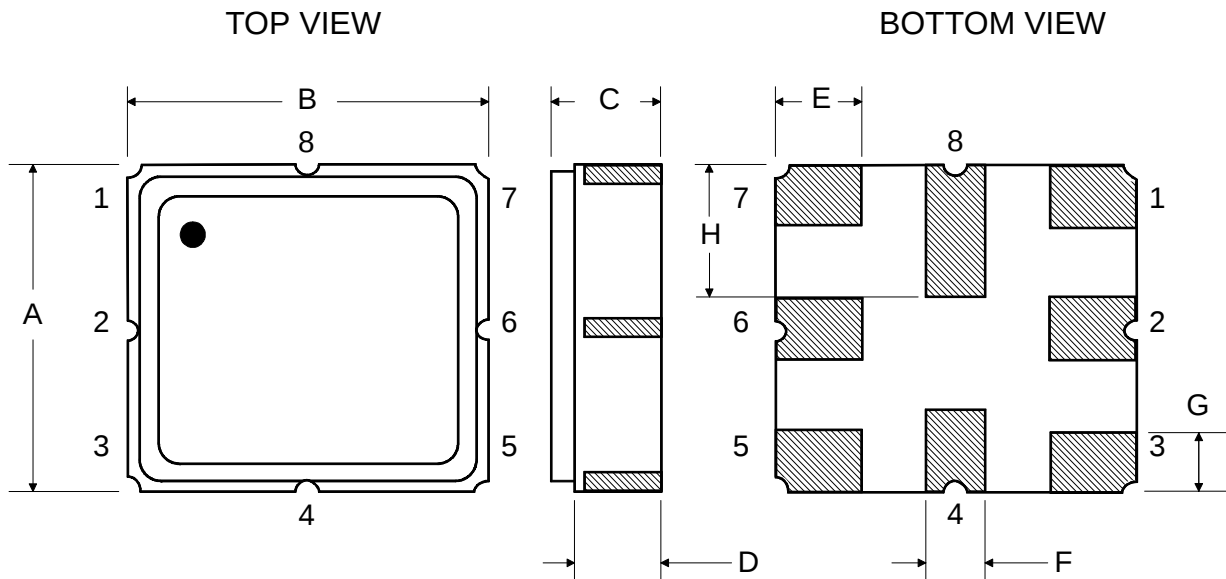


Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.0	3.13	0.113	0.118	0.123
B	2.87	3.0	3.13	0.113	0.118	0.123
C	1.0	1.1	1.2	0.035	0.039	0.043
D	0.79	0.92	1.05	0.031	0.036	0.041
E	0.62	0.75	0.88	0.024	0.029	0.034
F	0.47	0.60	0.73	0.018	0.024	0.029
G	0.47	0.60	0.73	0.018	0.024	0.029
H	1.07	1.20	1.33	0.042	0.047	0.052

	Connection	Terminals
	Balanced Input	1, 2
	Balanced Output	5, 6
	Ground	All Others

Dot Indicates Pin 1

Materials	
Solder Pad Termination	Au plating 30 - 60 μinches (76.2-152 μm) over 80-200 μinches (203-508 μm) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 μinches Thick
Body	Al ₂ O ₃ Ceramic
Pb Free	





“B “ Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

